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# Monica Laurel Kempsell

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<b>Objective</b>	To complete a PhD degree with an emphasis in photolithography at Rochester Institute of Technology.		
<b>Education</b>	Rochester Institute of Technology	2007 – Current	Rochester, NY
	Microsystems Engineering		
<b>Work Experience</b>	Oregon State University	2004 - 2007	Corvallis, OR
	B.S. in Electrical Engineering		
	Minor in Physics		
	G.P.A.: 3.95/4.0		
<b>Work Experience</b>	Intel Corporation	June '06 - August '06	Hillsboro, OR
	Technical Intern: Developed design rules for a future generation of technology in Portland Technology Development (PTD) Resolution Enhancement Techniques (RET) Group. Learned how to parametrically generate patterns, simulate with a lithography model, and determine feasibility by analysis.		
	Intel Corporation	June '05 - August '05	Hillsboro, OR
	Technical Intern: Characterized a photoresist to obtain the relationship between focus and bright band width for Advanced Process Control in Fab 20 Copper Lithography. Performed focus/exposure and swing curve analysis to reduce bias between nested and isolated features in order to qualify a tool on via layers.		
	Intel Corporation	June '04 –August '04	Aloha, OR
	Technical Intern: Developed a multilayer resist process using a bottom anti-reflective coating for a future generation in the lithography team of Storage Technology Group. Learned optimization techniques such as focus exposure arrays and swing curves.		
<b>Activities and Honors</b>	Intel Corporation	June '03 –August '03	Hillsboro, OR
	Technical Intern: Optimized a Carbon Doped Oxide dielectric recipe for a CVD tool in PTD. Learned functionality of metrology tools to characterize the film's surface.		
	Intel Corporation	June '02 –August '02	Aloha, OR
	Technical Intern: Processed production wafers and performed preventative maintenance as a Self Sustaining Technician in Fab 15 I-line Photolithography.		
<b>Activities and Honors</b>	Dean's List, Intel Honors Internship Program, IEEE, SWE, TBP, HKN Electrical Engineering Society (President '06-'07), OSA (President '06-'07), Mortar Board Senior Honor Society, Undergraduate Research, Innovation, Scholarship and Creativity (URISC) Awardee ('06-'07).		

